



SOM-COMe-CT6-TWL

COM Express Rel. 3.1 Type 6 Module with Intel® Core™ i3 processor, Intel® Processors N Series (Codename: Twin Lake)

Intel® Next Gen Atom® processors in high-performance, versatile COM Express® with rugged efficiency



HIGHLIGHTS



CPU

Intel® Core™ i3 processor, Intel® Processors N Series (Codename: Twin Lake)



GRAPHICS

Integrated Intel® Graphics with up to 32 Execution Units, supporting 3 independent displays



CONNECTIVITY

1 x NBase-T (2.5GbE supported); 8x Hi-Speed USB; Up to 1 x USB 10Gbps + 3x USB 5Gbps; 6x PCI-e lanes Gen3



MEMORY

One DDR5 SO-DIMM slot supporting DDR5-4800 IBECC Memory, up to 16GB



Windows 11



MAIN FIELDS OF APPLICATION



Medical



Transportation

Industrial
AutomationSmart Buildings &
Smart Cities

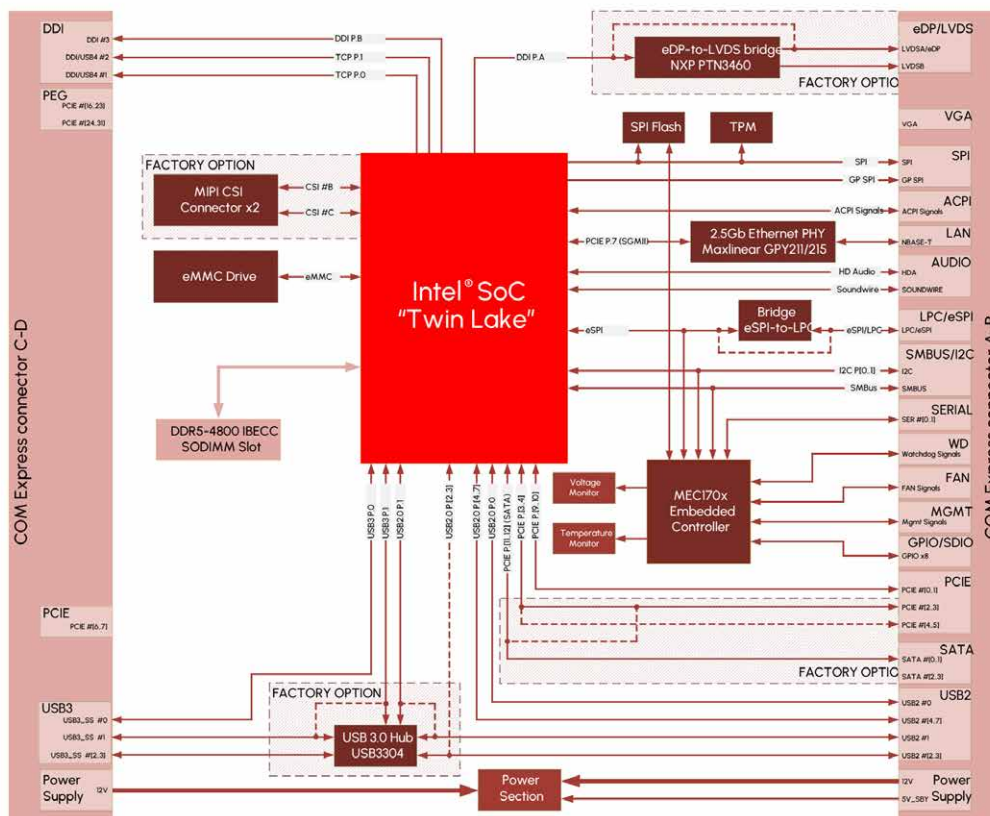
FEATURES

Processor	Intel® Core™ i3 processor and Intel® Processors N Series (Codename: Twin Lake):	PCI-e	Up to 6x PCI-e Gen3 lanes
	- Intel® Core™ i3-N355, 8 Cores @1.9 GHz (3.9 GHz Turbo), 15W TDP - Intel® Processor N250, 4 Cores @1.3 GHz (3.8 GHz Turbo), 6W TDP - Intel® Processor N150, 4 Cores @0.8 GHz (3.6 GHz Turbo), 6W TDP	Audio	HD Audio interface SoundWire Interface
Memory	1x DDR5-4800 SODIMM Slots, max capacity 16GB supported IBECC In-Band Error Correction Code Supported	Serial Ports	2x UARTs
Graphics	Integrated Intel® Graphics driven by Intel® Xe architecture: Support DirectX 12.1, OpenGL 4.6, Vulkan 1.2, Mesa 3D HW accelerated video decode & encode AVC, HEVC, VP9, SCC	Other Interfaces	SPI, 2x I2C, SM Bus, Thermal Management, FAN management Optional eSPI or LPC bus (factory alternatives) Optional TPM 1.2/2.0 on-board LID#/SLEEP#/PWRBTN#, watchdog 4x GPI, 4x GPO Optional 2x CSI camera interfaces
Video Interfaces	2x Digital Display Interfaces (DDIs), supporting DP, HDMI®, DP Alt-Mode over Type-C 1x DDI Interface supporting DP / HDMI® 1x eDP or Single/Dual-Channel 18-/24-bit LVDS interface (factory alternatives) Optional 2x MIPI CSI-2 4-lanes inputs	Power Supply	+12V _{DC} ± 10%
Video Resolution	Up to 3x4K60 SDR (DDI interfaces) Up to 1080p 60Hz (eDP) / 1920x1200 @ 60Hz (LVDS)	Operating System	Clea OS Microsoft® Windows 11 IoT Enterprise
Mass Storage	Up to 2x external S-ATA Gen3.2 channels Optional eMMC 5.1 drive soldered on-board, max size 128GB	Operating Temperature*	0°C ÷ +60°C (Commercial version)
Networking	1x NBase-T ethernet ports (2.5GbE supported) MaxLinear GPHY211 or GPHY215 2.5 GbE PHY on processor's SGMII interface	Dimensions	95 x 95 mm (COM Express® Compact Form factor, Type 6 pinout)
USB	up to 2x USB 10Gbps interfaces (Without USB Hub) optional 3x USB 5Gbps (with USB HUB) 8x Hi-Speed USB	*Measured at any point of SECO standard heatspreader for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application-specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated	

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BLOCK DIAGRAM



Streamline and expedite your edge computing implementations

Clea OS

A flexible operating system that adapts to your needs, thanks to the customization tool and Docker support. Reliability and security are built-in through a dual-partition system and native integration with Exein's robust AI-based protection.

Clea Astarte

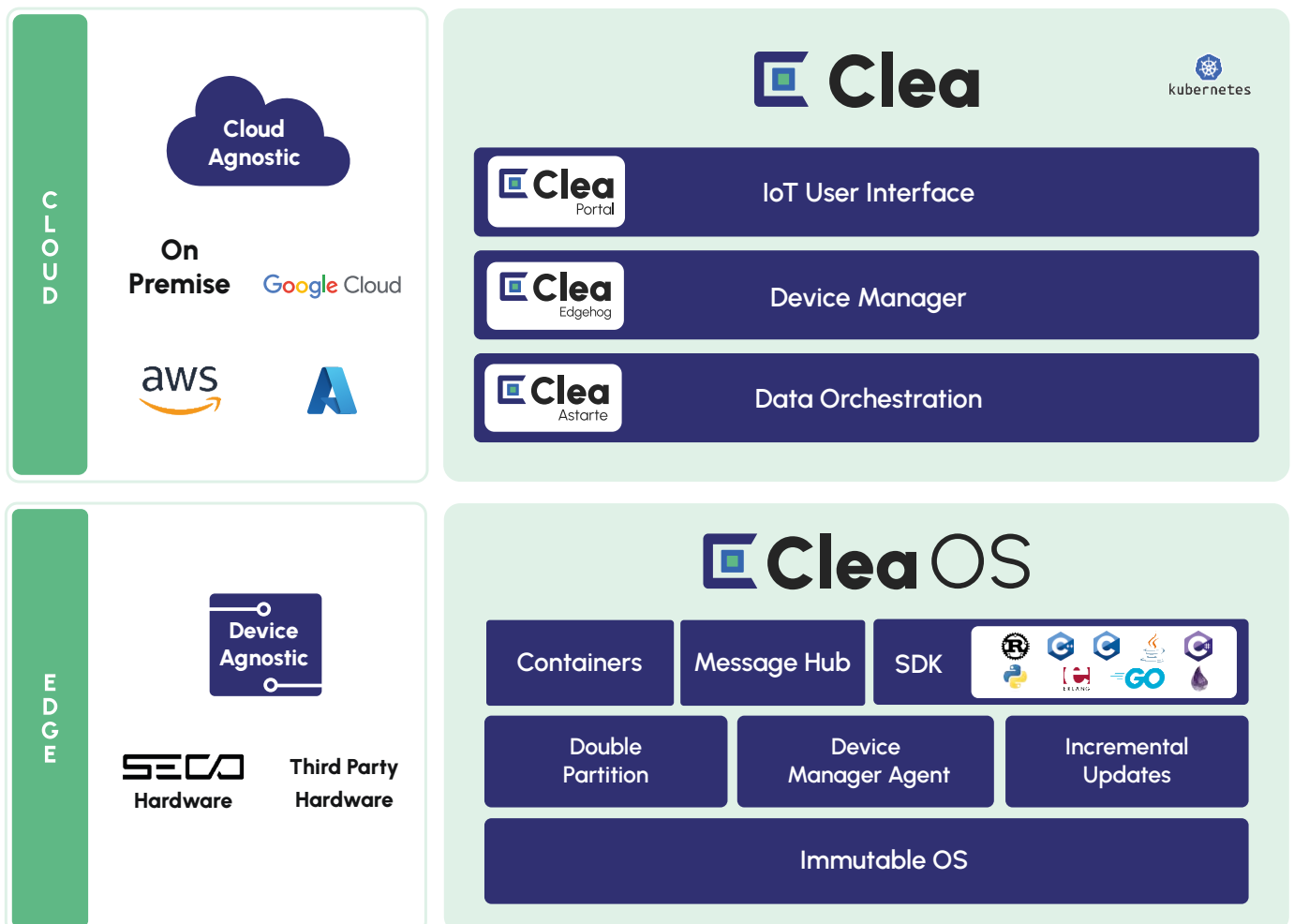
Integrate third-party services, simplify data flows and analysis, and enhance business efficiency by enabling easy and fast utilization of AI.

Clea Edgehog

Update, configure, and manage remote devices. Optimize time and costs to maximize operational efficiency and security without the need for costly field interventions.

Clea Portal

Analyze data from remote devices, customize the user experience with applications tailored to user needs, and manage user rights, company access, and tenant privileges.



Scan to know more about our solution

Clea OS



Clea DOCS

